Final Call for Papers

CAD, Design and Test Conference
Chair: Peter Schneider, Fraunhofer IIS/EAS, Dresden, Germany
Co-Chair: Francis Pressecq, CNES, France

Microfabrication, Integration and Packaging Conference
Chair: Stewart Smith, Univ. of Edinburgh, Scotland
Co-Chair: Yoshio Mita, The University of Tokyo, Japan

INVITATION TO PARTICIPATE
DTIP’2019 will be the 20th anniversary edition of the Symposium on Design, Test, Integration & Packaging of MEMS and MOEMS. This unique event brings together participants interested in MEMS/MOEMS processing and those interested in design tools and methods to facilitate the design of MEMS/MOEMS. All aspects including design, modeling, testing, micro-machining, integration and packaging of structures, devices and systems are addressed in two main Conferences, Special Sessions and Invited Talks. Papers presented at the conference will appear in IEEE Xplore and extended version of the presented papers may be submitted for inclusion in a special issue of an indexed journal.

We look forward to welcoming you in Paris next Spring.
Jérôme Juillard, Elie Lefevre & Pascal Nouet

It’s time to prepare your scientific contributions!

Research paper submission
DTIP aims to present the latest research in “Design, Integration, Test and Packaging of MEMS and MOEMS”. A program committee composed with international experts in their field will review all submitted papers. Even if abstracts of about 600 words will be considered, it is highly recommended to submit extended abstracts (up to 1500 words) plus one page of figures for efficient and fair scientific reviewing. Detailed instructions regarding electronic submissions are posted on the DTIP website.

Note: Companies that want to advertise their products are discouraged to submit a research paper if there is no revelation of any scientific contribution or rupture with respect to the state-of-the-art. In that later case, it is recommended to consider becoming a sponsor/exhibitor of the conference.

Special sessions
For those of you, who intend to propose a special session, feel free to propose a topic by email (dtip@dtip-mems.org) at your earliest convenience. When proposing a special session, please mention how many submissions are expected. Special session organizers will be in charge of attracting papers, organizing the review and making the final selection with the support of the DTIP organization. The coupling of a special session with an invited talk is strongly recommended.

Invited talks and panels
The symposium program will include three plenary sessions with invited talks and/or technical panels. Feel free to propose topics to be addressed and/or to nominate colleagues for an invited talk.

Venue and important dates
The 2019’s edition of DTIP will be held in downtown Paris, France, from May 12th till May 15th. Important dates are:

Notification of Acceptance: February 8th, 2019.
Camera-ready Due and Early bird registration: April 5th, 2019.

Detailed information on Submission - Exhibition - Sponsoring - Advertising at:

http://dtip-mems.org/